Transmitted herewith for filing is the Patent Application of:

mentor: CHII-MING WU, MEI-YUN WANG, CHIH-WEI CHANG, SHAU-LIN SHUE

METHOD OF FORMING METAL SILICIDE

Enclosed are:

x	3 sheets of drawing(s) - formal.
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.
	An associate power of attorney Applicant claims small entity status
	Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN	A SMALL ENTITY
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE	><	><		\$ 770.
TOTAL CLAIMS	27 -20=	7	x 18 =	\$ 126.
INDEP CLAIMS	3 -3=	0	x 86 =	\$ 0.
		SI	UB TOTAL	\$ 896.
		A	SSIGNMENT	\$40.
		T	OTAL	\$ 936.

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Any patent application processing fees under 37 CFR §1.17.

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and of Attorney requests the date of deposit as the Filing Date.

Signature / Date